



# 2017 ISC

## Press Kit

June 19, 2017

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Intel is transforming the future of high-performance computing (HPC) with new tools for innovation and discovery. At this year's International Supercomputing Conference in Frankfurt, Intel is sharing updates to its HPC product portfolio that includes SDVis Appliance, a new turnkey solution for optimizing visualization, the upcoming Intel® Xeon® Scalable processor to enable new levels of performance and scalability, optimizations to the Intel® Omni-Path Architecture (Intel® OPA), an end-to-end fabric solution, and Intel's upcoming extension to Intel® Xeon Phi™ with Knights Mill, the first CPU tool targeted for deep learning model training.

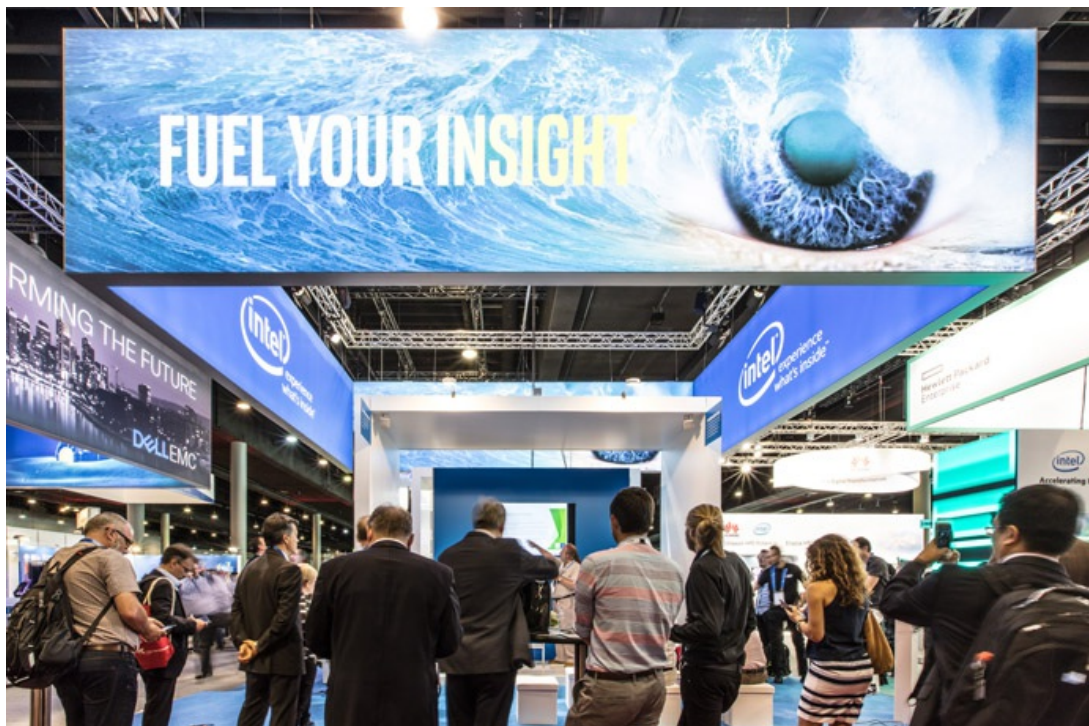
## Related Links on Newsroom

- [Intel Unveils Next Generation Technologies to Advance High Performance Computing and Artificial Intelligence Capabilities \(Fact Sheet\)](#)
- [Intel Demonstrates Future of High-Performance Computing and Artificial Intelligence Capabilities \(News Byte\)](#)
- [Enabling Innovation and Discovery Across the HPC Community \(Trish Damkroger Editorial\)](#)
- [Accelerating Deep Learning Workloads \(Barry Davis Editorial\)](#)

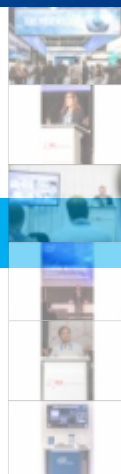
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ISC Keynote, Dr. Rajeeb Hazra

## Images







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Tags: High  
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